

Low Noise, Low Quiescent Current, 150mA Linear Regulator with Noise Bypass

FEATURES

- Very Low Noise, 25 μ V_{RMS} @ f=10~100kHz.
- Very Low Quiescent Current, 35 μ A.
- Very Low Dropout Voltage, 90mV @ 50mA.
- Active Low Shutdown Control.
- Short Circuit and Thermal Protection.
- 1.5V, 1.8V, 2.0V, 2.5V, 2.8V, 2.85V, 2.9V, 3.0V, 3.3V Output Voltage.

TYPICAL APPLICATION CIRCUIT

- Available in ±2% Output Tolerance.
- Low Profile Package: SOT-23-5

APPLICATIONS

- Cellular Telephones.
- Pagers.
- Personal Communication Equipment.
- Cordless Telephones.
- Portable Instrumentation.
- Portable Consumer Equipment.
- Radio Control Systems.
- Low Voltage Systems.
- Battery Powered Systems

DESCRIPTION

AIC1742 is a low noise, low dropout linear regulator, and is housed in a small SOT-23-5 package. The device is in the "ON" state when the SHDN pin is set to logic high level. A low dropout voltage of 90mV at 50mA load current is performed. It offers high precision output voltage of ±2%. The quality of low quiescent current and low dropout voltage makes this device ideal for battery power applications. The internal reverse bias protection eliminates the requirement for a reverse voltage protection diode. The high ripple rejection and low noise of AIC1742 provide enhanced performance for critical applications. The noise bypass pin can be connected an external capacitor to reduce the output noise level.



Low Noise Low Dropout Linear Regulator



ORDERING INFORMATION

AIC1742-<u>XXX XXX XX</u>

PACKING TYPE
TR: TAPE & REEL
BG: BAG

C: COMMERCIAL ACV: SOT-23-5 BCV: SOT-23-5

> P: LEAD FREE COMMERCIAL APV: SOT-23-5 BPV: SOT-23-5

G: GREE PACKAGE AGV: SOT-23-5 BGV: SOT-23-5

OUTPUT VOLTAGE

- 15: 1.5V 18: 1.8V
- 18: 1.8 v 20: 2.0V
- 20: 2.00
- 25: 2.5V
- 28: 2.8V
- 285: 2.85V
- 29: 2.9V
- 30: 3.0V
- 33: 3.3V

(Of a unit of 0.1V within the voltage range from 1.5V to 3.3V, additional voltage versions for this product line may be available on demand with prior consultation with AIC.)







• SOT-23-5 Marking

Part No.	ACV	APV	AGV	Part No.	BCV	BPV	BGV
AIC1742-15AXV	ER15	ER15P	ER15G	AIC1742-15BXV	ES15	ES15P	ES15G
AIC1742-18AXV	ER18	ER18P	ER18G	AIC1742-18BXV	ES18	ES18P	ES18G
AIC1742-20AXV	ER20	ER20P	ER20G	AIC1742-20BXV	ES20	ES20P	ES20G
AIC1742-25AXV	ER25	ER25P	ER25G	AIC1742-25BXV	ES25	ES25P	ES25G
AIC1742-28AXV	ER28	ER28P	ER28G	AIC1742-28BXV	ES28	ES28P	ES28G
AIC1742-285AXV	ER2J	ER2JP	ER2JG	AIC1742-285BXV	ES2J	ES2JP	ES2JG
AIC1742-29AXV	ER29	ER29P	ER29G	AIC1742-29BXV	ES29	ES29P	ES29G
AIC1742-30AXV	ER30	ER30P	ER30G	AIC1742-30BXV	ES30	ES30P	ES30G
AIC1742-33AXV	ER33	ER33P	ER33G	AIC1742-33BXV	ES33	ES33P	ES33G

ABSOLUTE MAXIMUM RATINGS

Supply Voltage	9V
Shutdown Terminal Voltage	
Power Dissipation	500mW
Operating Temperature Range	
Maximum Junction Temperature	125°C
Storage Temperature Range	-65°C~150°C
Lead Temperature (Soldering, 10 sec)	260°C
Thermal Resistance Junction to Case	130°C/W
Thermal Resistance Junction to Ambient	220°C/W
(Assume no ambient airflow, no heatsink)	

Absolute Maximum Ratings are those values beyond which the life of a device may be impaired.

TEST CIRCUIT

Refer to TYPICAL APPLICATION CIRCUIT



ELECTRICAL CHARACTERISTICS

(T_J=25°C, unless otherwise specified) (Note1)

PARAMETER	TEST CONDITIONS		SYMBOL	MIN.	TYP.	MAX.	UNIT
Quiescent Current	V _{IN} = V _{OUT} + 1V, V _{SHDN} =1.6V, I _{OUT} = 0mA		ΙQ		35	45	μA
Standby Current	V _{IN} = V _{OUT} + 1V to 8V, V _{SHDN} =0.6V, Output OFF		I _{STBY}			0.1	μA
GND Pin Current	I _{OUT} = 50mA		I _{GND}		2.5	3.5	mA
Continuous Output Current	V _{IN} = V _{OUT} + 1V	′ to 8V	I _{OUT}			150	mA
Output Current Limit	$V_{IN} = V_{OUT} + 1V$	/, V _{OUT} = 0V	١ _L	150	250		mA
Output Voltage Tolerance	V _{IN} = V _{OUT} + 1V, no load		V _{OUT}	-2		2	%
Temperature Coefficient			T _C		50	150	ppm/ºC
Line Regulation	$V_{IN} = V_{OUT(TYP)} + 1V \text{ to } 8V$		ΔV_{LIR}		2	5	mV
Load Regulation	V _{IN} = 5V, I _{OUT} = 0.1~150mA		ΔV_{LOR}		0.005	0.01	%/mA
Dropout Voltage	l _{OUT} = 50 mA				90	160	- mV
	I _{OUT} = 100 mA	Vout≥2.5V			140	230	
	I _{OUT} = 150 mA		V _{DROP}		200	350	
	I _{OUT} = 150 mA	Vout<2.5V			500	800	
Noise Bypass Terminal Voltage		1	V _{REF}		1.25		V
Ripple Rejection	f=1KHz, Ripple=0.5V _{P-P} , C _{BP} = 0.1μF		RR		65		dB
Output Noise	C _{BP} = 0.1μF, f = 10~100KHz		en		25		μVrms
SHUTDOWN TERMINAL SPI	ECIFICATIONS						1
Shutdown Pin Current	V _{SHDN} =1.6V		ISHDN			2	μA
Shutdown Pin Voltage (ON)	Output ON		$V_{\overline{SHDN}}$ (ON)	1.6			V
Shutdown Pin Voltage (OFF)	Output OFF		V SHDN (OFF)			0.6	V
Shutdown Exit Delay Time	$C_{BP} = 0.1 \mu F, C_{OUT} = 1 \mu F,$ $I_{OUT}=30 m A$		∆t		300		μS

Note 1: Specifications are production tested at TA=25°C. Specifications over the -40°C to 85°C operating temperature range are assured by design, characterization and correlation with Statistical Quality Controls (SQC).

Note 2: The dropout voltage is defined as $V_{IN} - V_{OUT}$ when V_{OUT} is 1% below the value of V_{OUT} for $V_{IN} = V_{OUT} + 0.5V$. (Only applicable for $V_{OUT} = 2.5V \sim 5V$)





TYPICAL PERFORMANCE CHARACTERISTICS





TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

AIC1742

V_{SHDN}, 2V/Div

V_{OUT}, 1V/Div

M40.0µs A Ch2 l 900mV

Vin 500mV/Div

Vout, 20mV/Div

50.00 %

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TYPICAL PERFORMANCE CHARACTERISTICS (Continued)



Fig. 17 Transient Response 2



n standiger (d. 1997). Na standiger (d. 1997)

10 mVolt Fig. 18 Load Transient Response

lout, 50mA/Div

1) Ch 1: 20 mVolt 10 us

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TYPICAL PERFORMANCE CHARACTERISTICS (Continued)



BLOCK DIAGRAM



PIN DESCRIPTIONS

- VIN PIN Power supply input pin. Bypass with a 1µF capacitor to GND.
- GND PIN Ground pin.
- SHDN PIN- Active-Low shutdown input pin.
- BP PIN Noise bypass pin. An external bypass capacitor connecting to BP pin to reduce noises at the output.
- VOUT PIN Output pin. Sources up to 150 mA.



DETAILED DESCRIPTION OF TECHNICAL TERMS

DROPOUT VOLTAGE (VDROP)

The dropout voltage is defined as the difference between the input voltage and output voltage at which the output voltage drops 100mV. Below this value, the output voltage will fall as the input voltage reduces. It depends on the load current and junction temperature.

LINE REGULATION

Line regulation is the ability of the regulator to maintain a constant output voltage as the input voltage changes. The line regulation is specified as the input voltage changes from $V_{IN} = V_{OUT} + 1V$ to $V_{IN} = 8V$ and $I_{OUT} = 1$ mA.

LOAD REGULATION

Load regulation is the ability of the regulator to maintain a constant output voltage as the load current changes. A pulsed measurement with an input voltage set to $V_{IN} = V_{OUT} + V_{DROP}$ can minimize temperature effects. The load regulation is specified by the output current ranging from 0.1mA to 150mA.

QUIESCENT CURRENT (IQ)

Quiescent current is the current flowing through ground pin with no output load.

GROUND CURRENT (IGND)

Ground current is the current flowing through the ground pin with output load.

STANDBY CURRENT (ISTBY)

Standby current is the current flowing into the regulator when the output is shutdown by setting $V_{\overline{SHDN}}$ at 0V and V_{IN} at 8 V.

CURRENT LIMIT (IIL)

Current limiting of AIC1742 monitors and controls the maximum output current, in case of a shorted output. It protects device from the damage resulting from any unexpected current.

RIPPLE REJECTION (RR)

Ripple rejection is the ability of the regulator to reduce voltage ripple, which comes from input, at output terminal. It is specified with a signal of $0.5V_{P-P}$ at 1KHz frequency applying to input, output capacitor at 2.2µF as well as a noise bypass of 0.1μ F. Ripple rejection, expressed in dB, is the ratio of output ripple to input.

THERMAL PROTECTION

Thermal sensor protects device when the junction temperature exceeds T_J = +155°C. It signals shutdown logic, turning off pass transistor and allowing IC to cool down. After the IC's junction temperature cools by 15°C, the thermal sensor will turn the pass transistor back on. Thermal protection is designed to protect the device in the event of fault conditions. For a continuous operation, do not exceed the absolute maximum junction-temperature rating of T_J = 150°C, or damage may occur to the device.



APPLICATION INFORMATION

INPUT-OUTPUT CAPACITORS

Linear regulators require input and output capacitors to maintain stability. Input capacitor at 1µF with 1uF aluminum electrolytic or 2.2µF ceramic output capacitor is recommended. And it should be selected within the Equivalent Series Resistance (ESR) range as shown in the figure 20,21. ESR of ceramic capacitor is lower and its electrical characteristics (capacitance and ESR) vary widely over temperature. In general, tantalum or electric output capacitor is suggested for heavy load. Normally, the output capacitor should be 1µF (aluminum electrolytic) at least and rates for operating temperature range. Note that it's important to check selected manufactures electrical characteristics (capacitance and ESR) over temperature.

NOISE BYPASS CAPACITOR

 0.01μ F bypass capacitor at BP pin reduces output voltage noise. And the BP pin has to connect a capacitor to GND.

POWER DISSIPATION

The maximum power dissipation of AIC1742 depends on the thermal resistance of its case and circuit board, the temperature difference between the die junction and ambient air, and the rate of airflow. The rate of temperature rise is greatly affected by the mounting pad configuration on the PCB, the board material, and the ambient temperature. When the IC mounting with good thermal conductivity is used, the junction temperature will be low even when large power dissipation applies.

The power dissipation across the device is

$$\mathsf{P} = \mathsf{I}_{\mathsf{OUT}} (\mathsf{V}_{\mathsf{IN}} - \mathsf{V}_{\mathsf{OUT}}).$$

The maximum power dissipation is:

 $P_{MAX} = \frac{(T_J - T_A)}{(R\theta_{JB} + R\theta_{BA})}$

Where T_J-T_A is the temperature difference between the die junction and the surrounding air, $R\theta_{JB}$ is the thermal resistance of the package, and $R\theta_{BA}$ is the thermal resistance through the PCB, copper traces, and other materials to the surrounding air.

As a general rule, the lower temperature is, the better reliability of the device is. So the PCB mounting pad should provide maximum thermal conductivity to maintain low device temperature.

GND pin performs a dual function of providing an electrical connection to ground and channeling heat away. Therefore, connecting the GND pin to ground with a large pad or ground plane would increase the power dissipation and reduce the device temperature.

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PHYSICAL DIMENSIONS

• SOT-23-5 (unit: mm)



s Y	SOT-23-5 MILLIMETERS				
M B					
0 L	MIN.	MAX.			
A	0.95	1.45			
A1	0.05	0.15			
A2	0.90	1.30			
b	0.30	0.50			
С	0.08	0.22			
D	2.80	3.00			
E	2.60	3.00			
E1	1.50	1.70			
е	0.95 BSC				
e1	1.90 BSC				
L	0.30	0.60			
L1	0.60 REF				
q	0°	8°			

- Note : 1. Refer to JEDEC MO-178AA.
 - Dimension "D" does not include mold flash, protrusions or gate burrs. Mold flash, protrusion or gate burrs shall not exceed 10 mil per side.
 - 3. Dimension "E1" does not include inter-lead flash or protrusions.
 - 4. Controlling dimension is millimeter, converted inch dimensions are not necessarily exact.

Note:

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